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R. H. H. H.
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John J. Kelly, Jr.



John J. Kelly, Jr. Reg. No.: 29,182

Examiner: A. Chambliss
Art Unit: 2814

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FEB 29 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: K. TATSUMI et al.
Serial No.: .09/632,910
Filed : .August 4, 2000
For : SEMICONDUCTOR DEVICE PROVIDED WITH LOW MELTING POINT METAL BUMPS AND PROCESS FOR PRODUCING SAME

Assistant Commissioner
for Patents
Washington, D.C. 20231

AMENDMENT

SIR:

Kindly amend the claims of the above-identified patent application as follows.

Cancel claims 1-15, i.e., cancel all the pending claims.

Add the following new claims 16-26.

--16 (New) A process for producing a semiconductor device comprising electrodes formed on a semiconductor chip, and bumps each consisting of a spherically formed metal ball having a given size, and adhesive bonded to the electrodes (8) for the attachment of the bumps, wherein each electrode (8) includes a layer of an electrode material (5) and at least one layer (6, 7) laminated to the layer of the electrode material (5) to avoid

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